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(12) **United States Design Patent** (10) **Patent No.:** **US D797,826 S**  
**Alfaro et al.** (45) **Date of Patent:** **\*\* \*Sep. 19, 2017**

(54) **CERAMIC BONDING TOOL WITH TEXTURED TIP**

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(\*) Notice: This patent is subject to a terminal disclaimer.

(\*\*) Term: **14 Years**

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(51) **LOC (10) Cl.** ..... **15-09**

(52) **U.S. Cl.**  
USPC ..... **D15/144**

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D15/122, 138, 144, 144.1, 144.2;  
219/121.39, 121.46, 121.45, 121.5,  
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CPC .. B23K 20/004; B23K 20/005; B23K 20/106;  
H01L 24/85  
See application file for complete search history.

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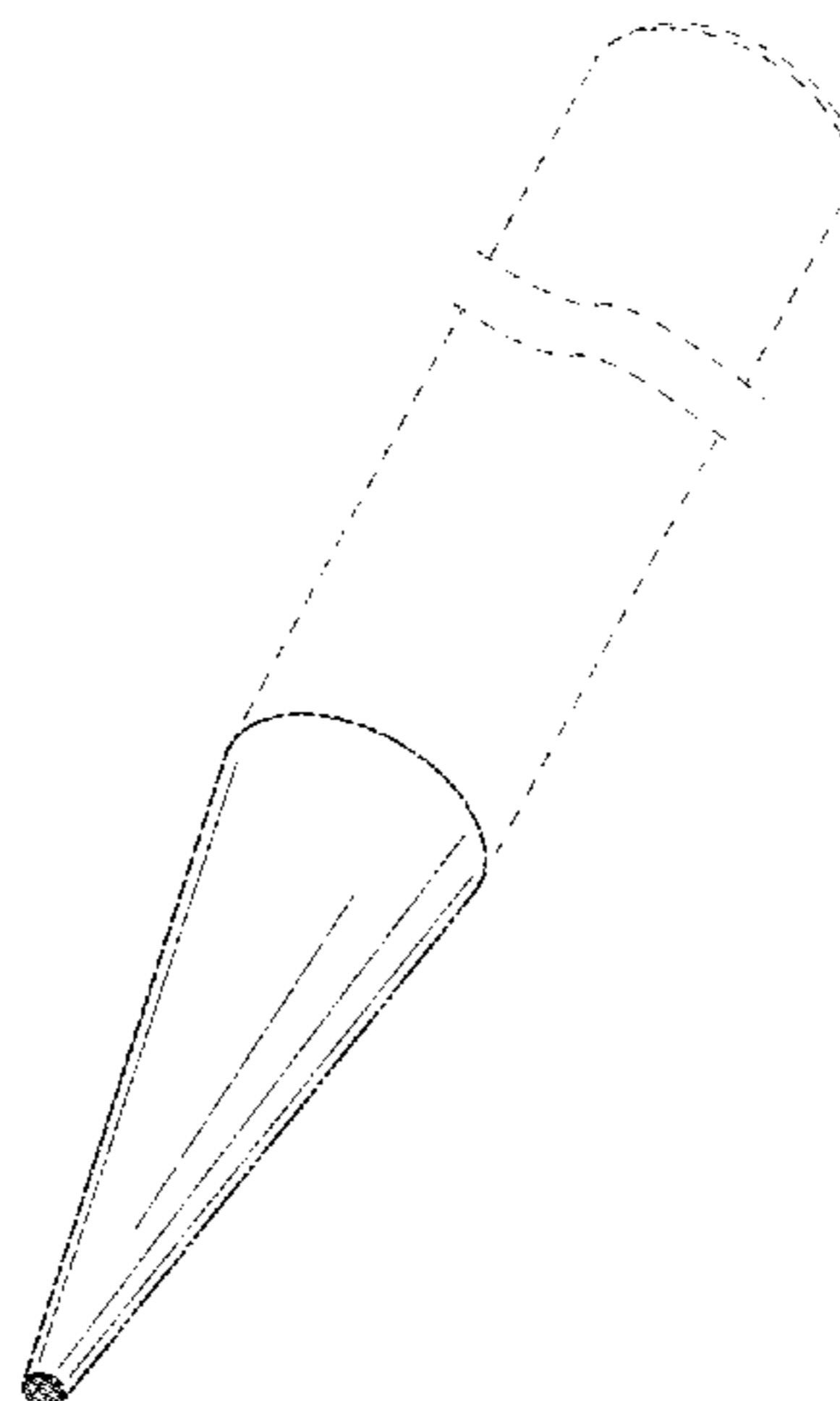
(57) **CLAIM**

The ornamental design for a ceramic bonding tool with textured tip, as shown and described.

**DESCRIPTION**

FIG. 1 depicts a perspective view of a ceramic bonding tool with textured tip.  
FIG. 2 depicts a side elevation view of the ceramic bonding tool with textured tip of FIG. 1.  
FIG. 3 depicts a top plan view of the ceramic bonding tool with textured tip of FIG. 1.  
FIG. 4 depicts a bottom plan view of the ceramic bonding tool with textured tip of FIG. 1.  
FIG. 5 depicts a detailed bottom plan view of the ceramic bonding tool with textured tip shown in FIG. 4; and,  
FIG. 6 depicts a detailed side cross-section view of the ceramic bonding tool with textured tip, the cross-section taken along cross-section indicator line 6-6 of FIG. 5.  
The broken lines in the drawings illustrate environmental structure on the article and form no part of the claimed design.

**1 Claim, 3 Drawing Sheets**



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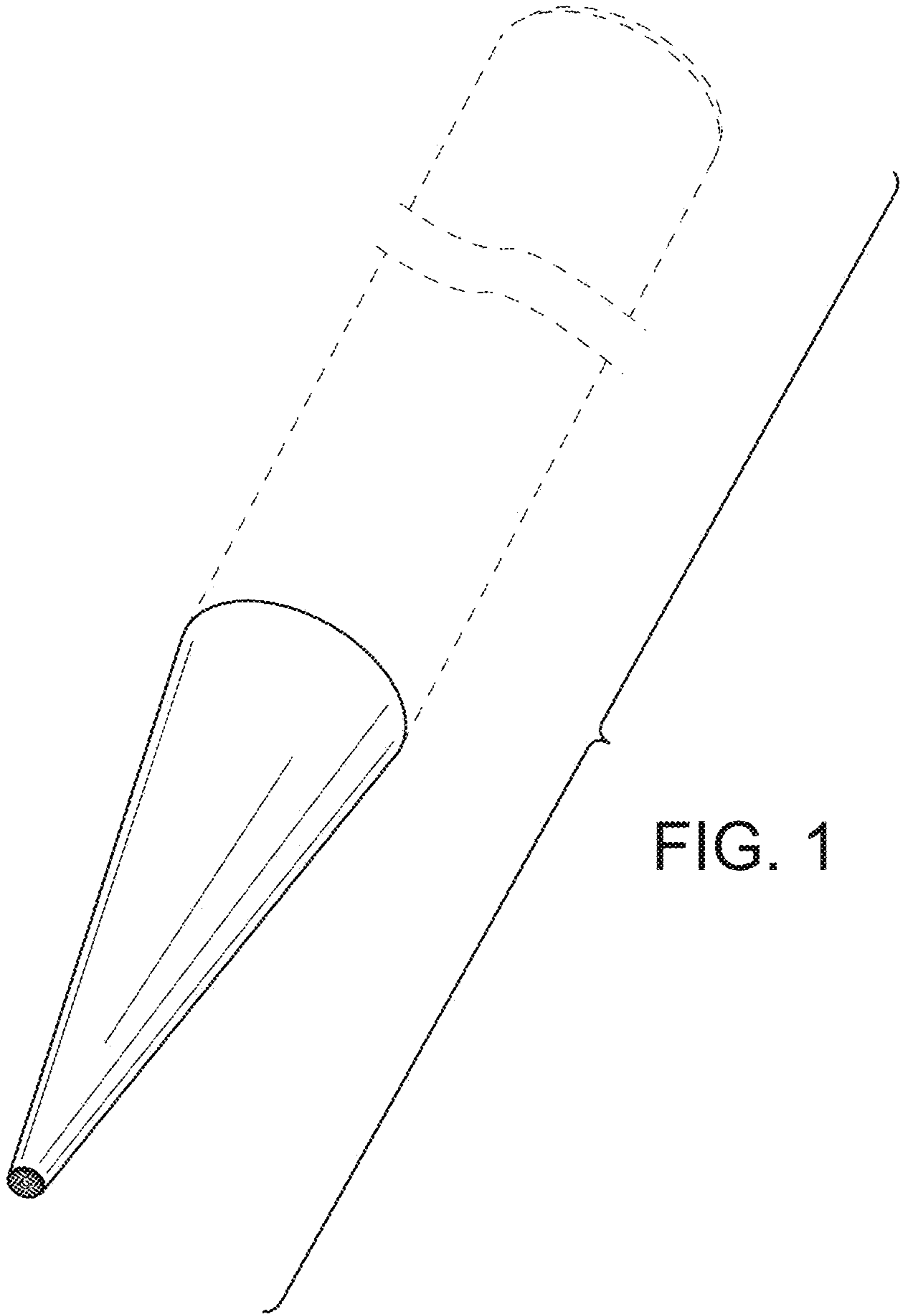


FIG. 1

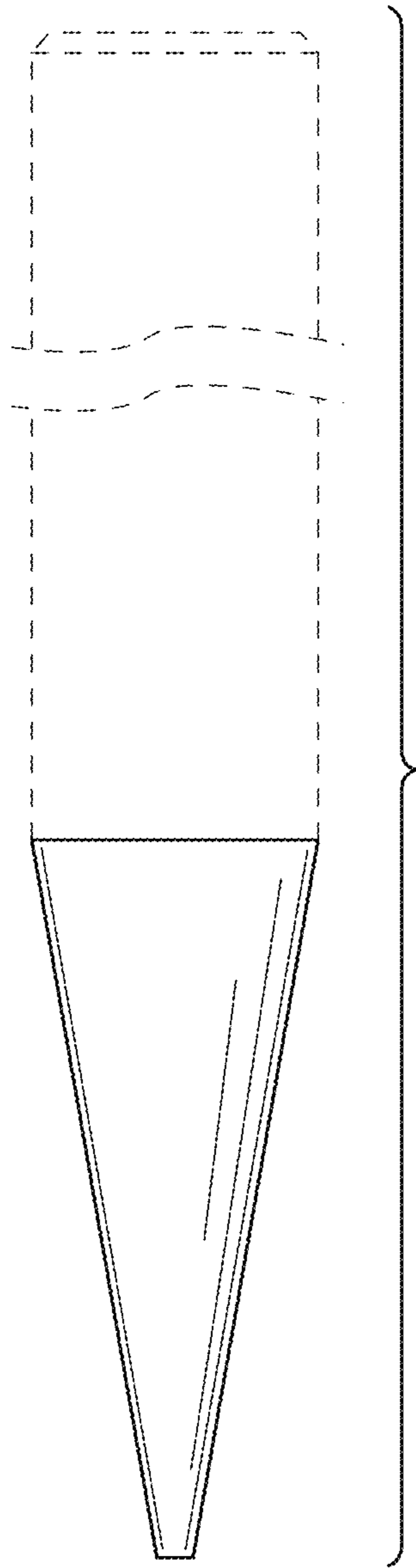


FIG. 2

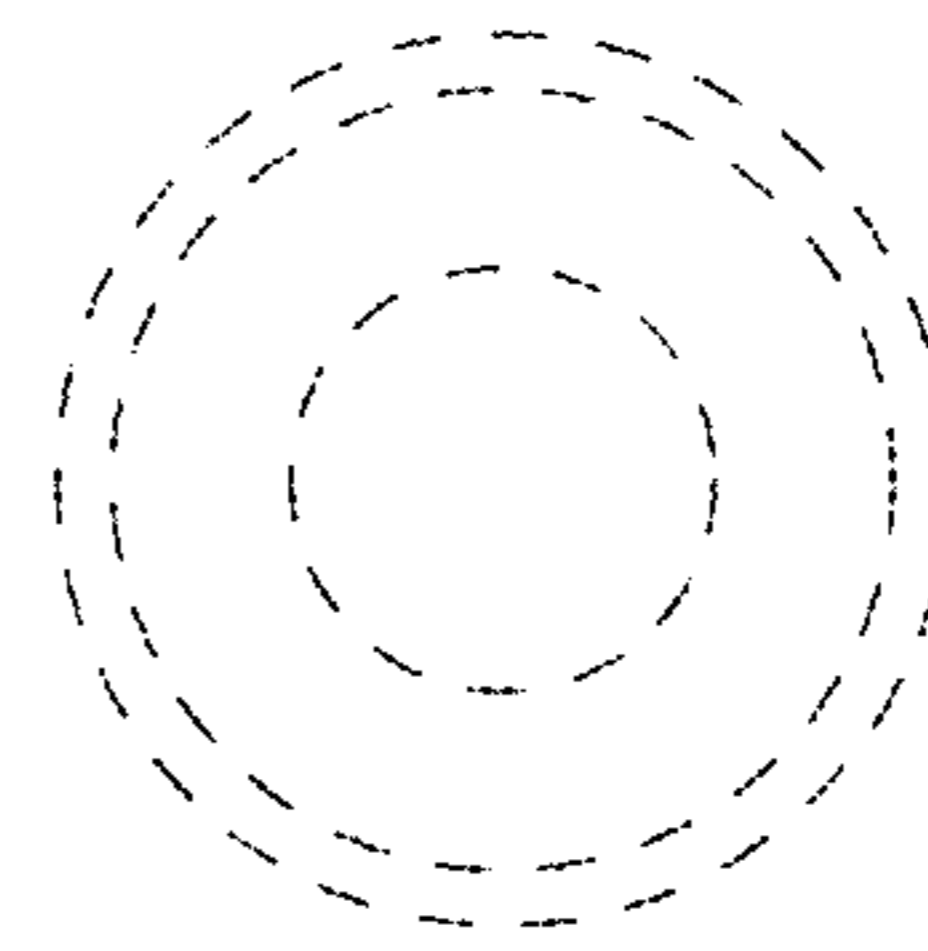


FIG. 3

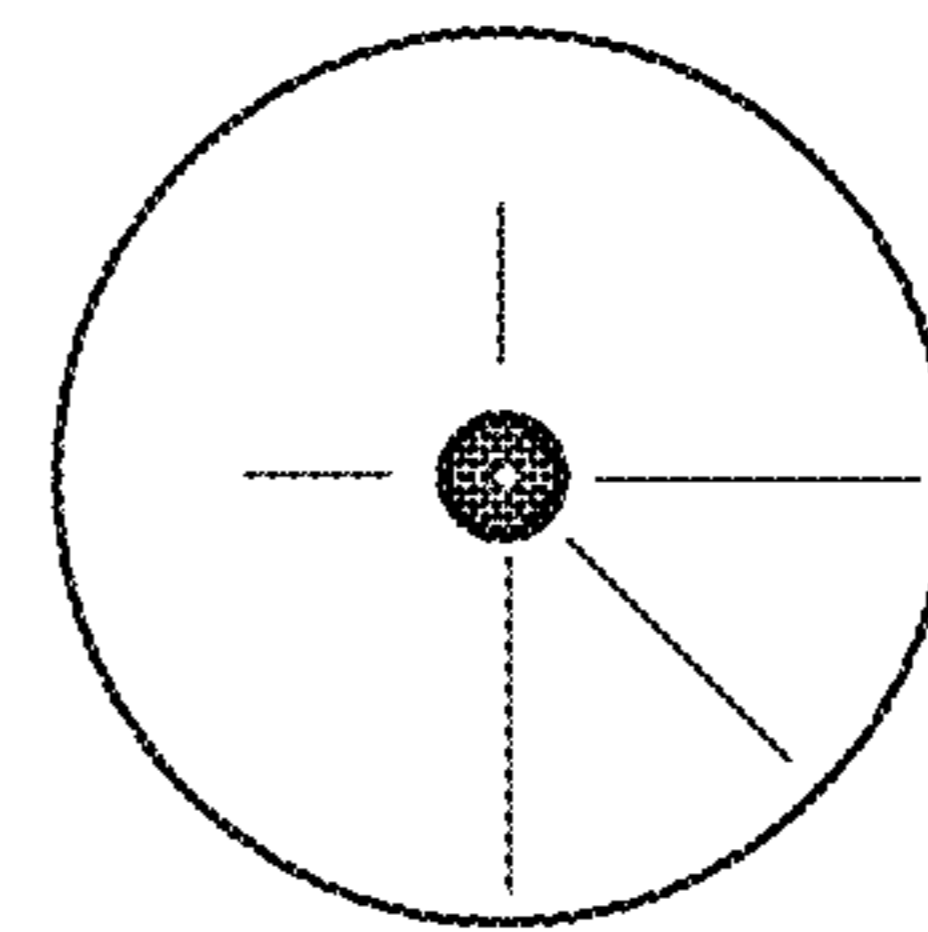


FIG. 4

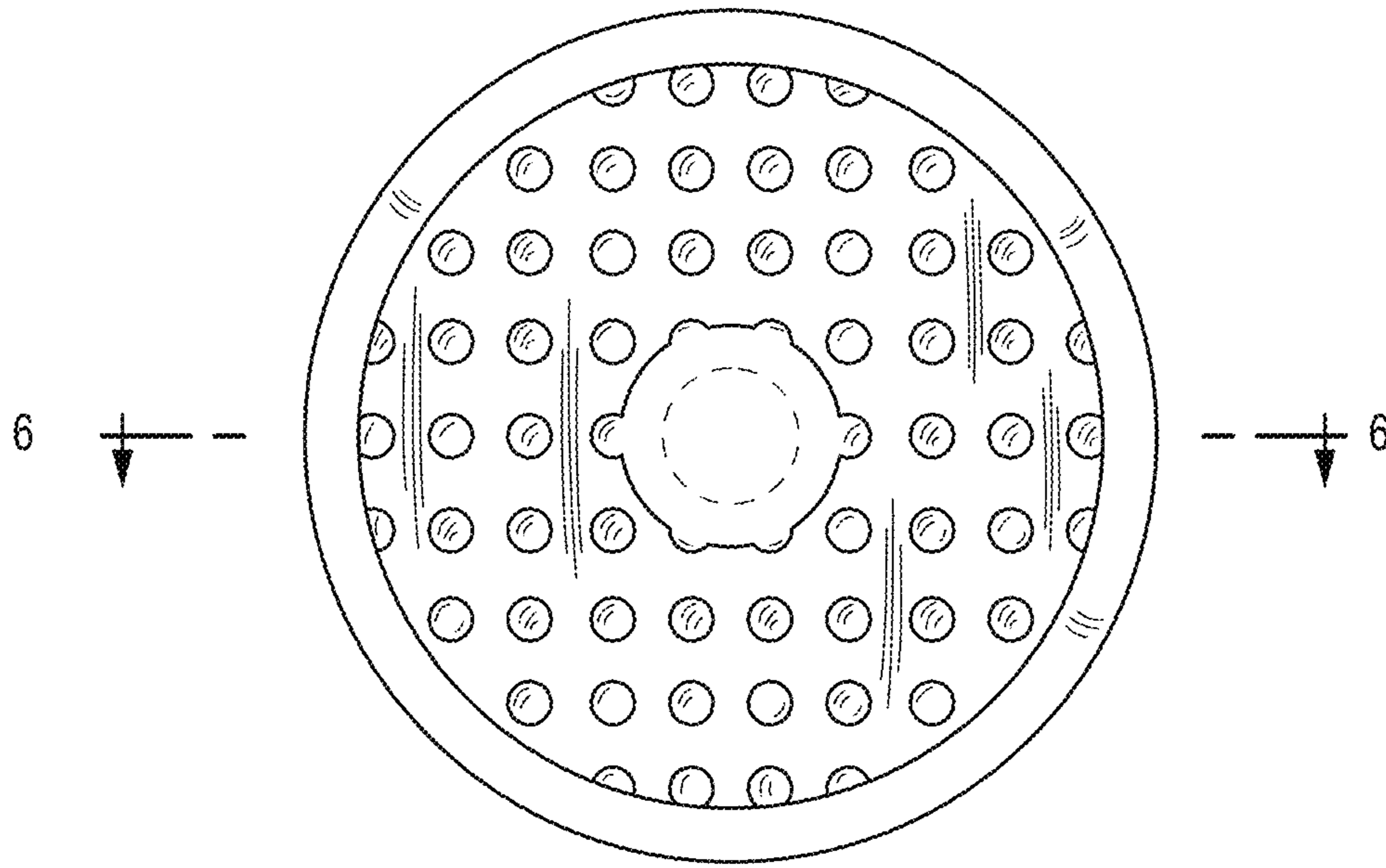


FIG. 5

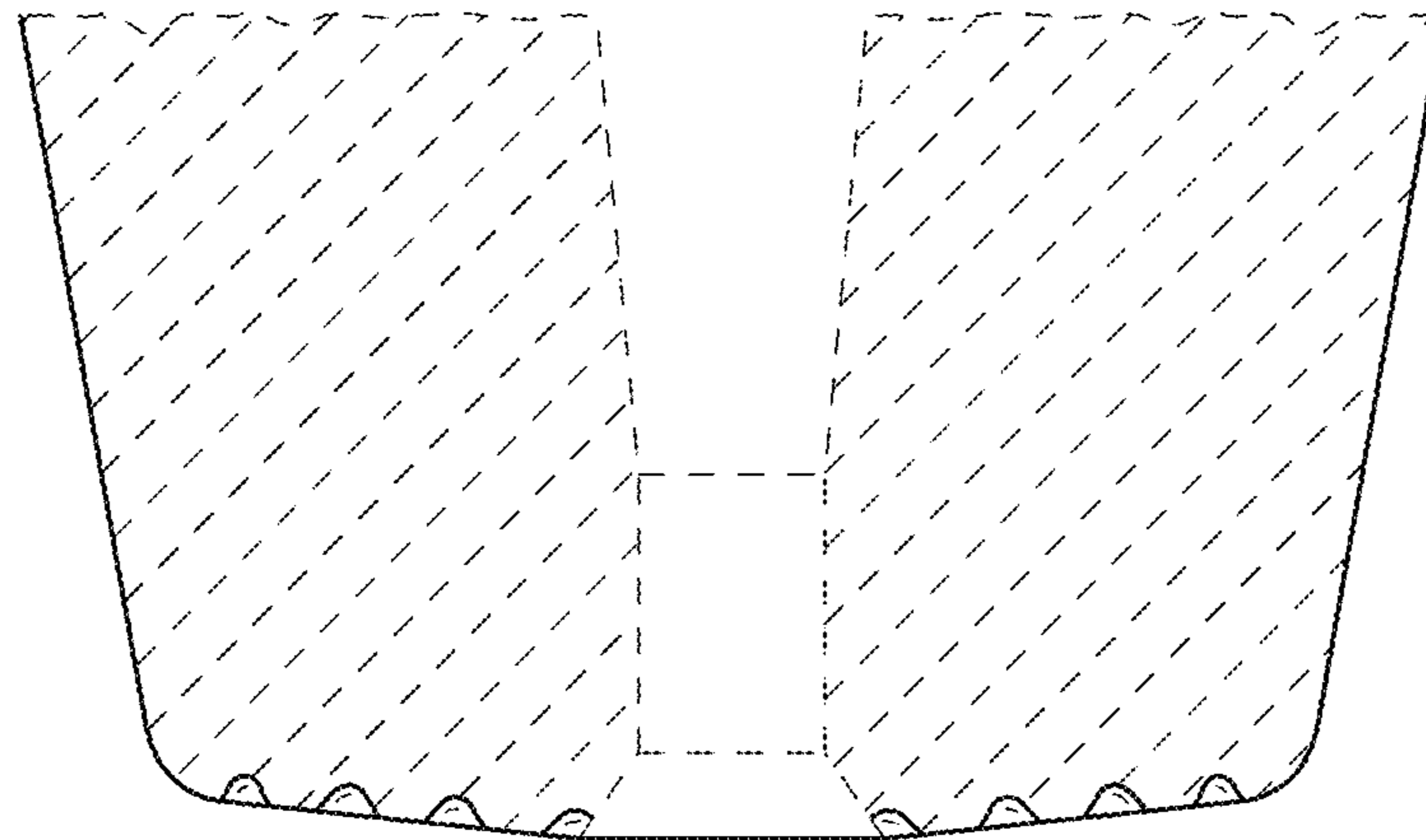


FIG. 6